

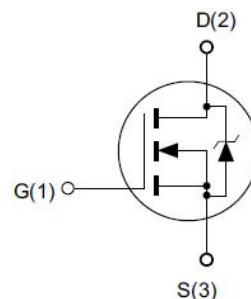


MPF20N50

N-Channel Power MOSFET

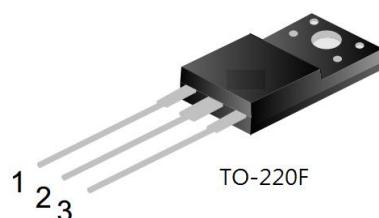
Features

- ◆ 500V, 20A, $R_{DS(ON)}$ (Typ.) = 0.24Ω@VGS = 10V.
- ◆ Fast Switching
- ◆ 100% Avalanche Tested



Application

- ◆ Adaptor
- ◆ Standby Power
- ◆ Switching power supply
- ◆ PFC



Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Limit	Unit
		TO-220F	
V_{DS}	Drain-Source Voltage ^a	500	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current-Continuous, $T_c = 25^\circ\text{C}$	20	A
	Drain Current-Continuous, $T_c = 100^\circ\text{C}$	12.5	A
I_{DM}	Drain Current-Pulsed ^b	80	A
P_D	Maximum Power Dissipation @ $T_J = 25^\circ\text{C}$	88	W
EAS	Single Pulsed Avalanche Energy ^d	980	mJ
T_J, T_{STG}	Operating and Store Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-Case Max.	1.42	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient Max.	62.5	$^\circ\text{C/W}$

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Off Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	500	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA
I_{GSS}	Forward Gate Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 30\text{V}$	-	-	± 100	nA



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■ On Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2	-	4	V
$R_{DS(on)}$	Static Drain-Source On-Resistance c	$V_{GS} = 10V$, $I_D = 10A$	-	0.24	0.30	Ω

■ Dynamic Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
C_{iss}	Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1.0MHz$	-	3059	-	pF
C_{oss}	Output Capacitance		-	291	-	pF
C_{rss}	Reverse Transfer Capacitance		-	16	-	pF

■ On Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250V$, $I_D = 20A$, $V_{GS}=10V$	-	35	-	ns
t_r	Turn-On Rise Time		-	64	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	83	-	ns
t_f	Turn-Off Fall Time		-	44	-	ns
Q_g	Total Gate Charge	$V_{DS} = 400V$, $I_D = 20A$, $V_{GS} = 10V$	-	54	-	nC
Q_{gs}	Gate-Source Charge		-	13.3	-	nC
Q_{gd}	Gate-Drain Charge		-	18.7	-	nC

■ Drain-Source Diode Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
I_s	Drain-Source Diode Forward Continuous Current	$V_{GS} = 0V$	-	-	20	A
I_{SM}	Maximum Pulsed Current	$V_{GS} = 0V$	-	-	80	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0V$, $I_s = 20A$	-		1.4	V
T_{rr}	Body Diode Reverse Recovery Time	$di/dt=100A/us$ $I_s=20A, V_{GS}=0V$	-	535	-	ns
Q_{rr}	Reverse Recovery Charge		-	6.4	-	uC

Notes:

- $T_J=+25^\circ C$ to $+150^\circ C$.
- Repetitive rating; pulse width limited by maximum junction temperature.
- Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
- $L=10mH$, $I_{AS}=14A$, $V_{DD}=50V$, $R_G=25\Omega$ Starting $T_J=25^\circ C$.

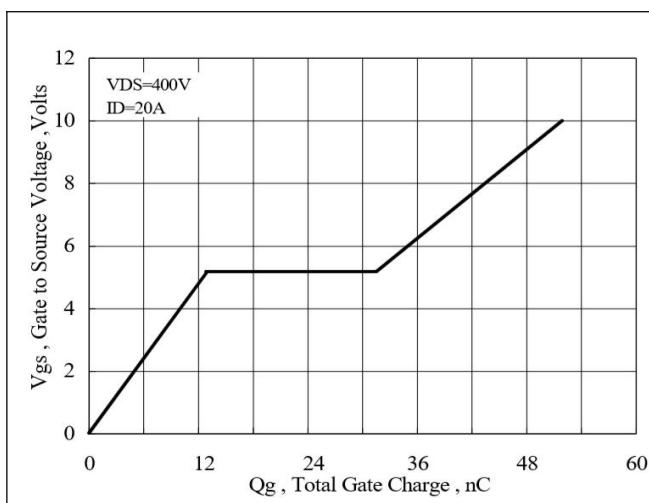


Figure 1. Gate Charge Characteristics

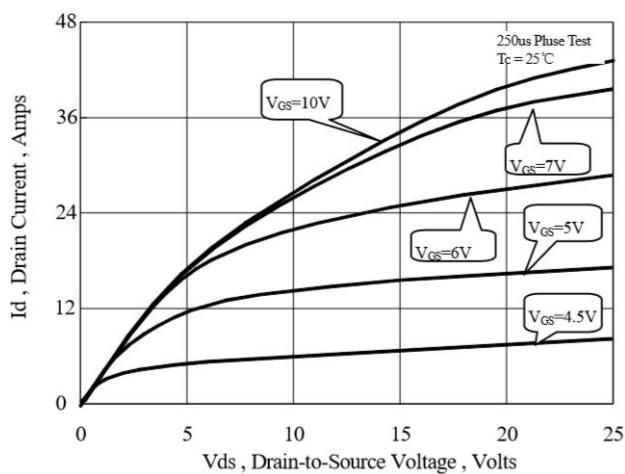


Figure 2. On-State Characteristics

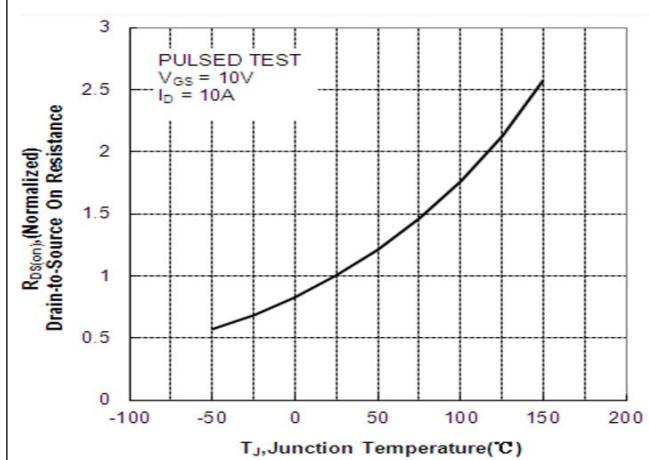


Figure 3. Normalized On-Resistance Variation with Temperature

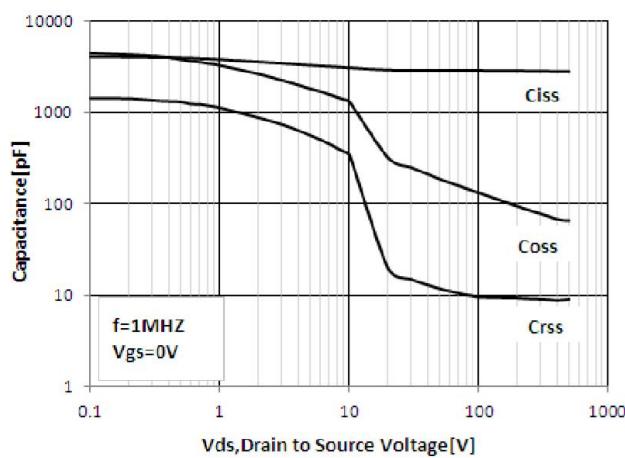


Figure 4. Typical Capacitance vs Drain to Source Voltage

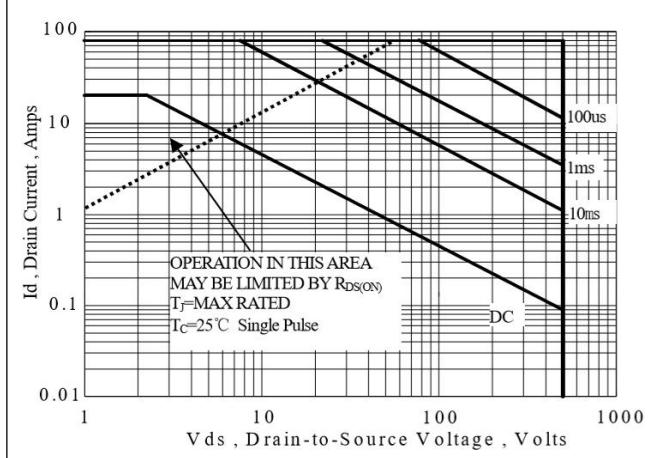


Figure 5. Maximum Forward Bias Safe Operating Area TO-220F

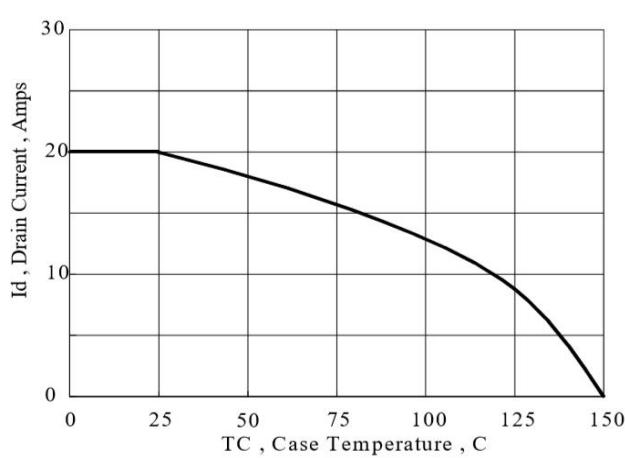


Figure 6. Maximum Continuous Drain Current vs Case Temperature

■ Package Information

